

SMD2016 SERIES PTC Devices

- The SMD2016 Halogen and Lead(Pb) Free Series, a polymer-based Positive Temperature Coefficient (PTC) device to protect electrical circuits against overcurrent conditions with resettable feature, is fully compatible with current industrial standards.
- The new designed SMD2016 Halogen and Lead(Pb) Free Series provides surface mount overcurrent protection with superior performance that is compliant with RoHS Directive 2002/95/EC.
- Application: The SMD2016 Halogen and Lead(Pb) Free Series is ideal for computers and peripherals and can be applied to almost anywhere there is a low voltage power supply and a load to be protected.
- The solder plated termination is designed to meet or exceed solderability specifications and provide excellent solder joint inspectability.
- Agency Approval: **UL/CSA File No.E201431**
TÜV Certificate # R50099121
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Polytronics Technology Corp
 REGISTERED TO QS9000, TL9000
 ISO9001 (version 2000), and ISO 14001
 CERTIFICATE NO.A8727 and A10971



ELECTRICAL CHARACTERISTICS

Part Number	I _{hold} (A)	I _{trip} (A)	V _{max} (Vdc)	I _{max} (A)	P _{d max.} (W)	Maximum Time To Trip		Resistance		Agency Approval	
						Current (A)	Time (Sec.)	R _{min} (Ω)	R _{1max} (Ω)	UL/CSA	TÜV
SMD2016P030TF	0.30	0.60	60	20	1.40	1.50	3.00	0.500	2.300	✓	✓
SMD2016P050TF	0.55	1.10	60	20	1.40	2.50	5.00	0.200	1.000	✓	✓
SMD2016P100TF	1.10	2.20	15	40	1.40	8.00	0.50	0.100	0.400	✓	✓
SMD2016P100TF/33	1.10	2.20	33	40	1.40	8.00	0.50	0.100	0.400	✓	✓
SMD2016P150TF	1.50	3.00	15	40	1.40	8.00	1.00	0.070	0.180	✓	✓
SMD2016P200TF	2.00	4.20	6	40	1.40	8.00	3.00	0.048	0.100	✓	✓

Note: I_{hold} = Hold current: maximum current device will pass without tripping in 20°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 20°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_d = Power dissipated from device when in the tripped state at 20°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

*Value specified were determined using the PWB with 0.090" * 1.5oz copper traces.

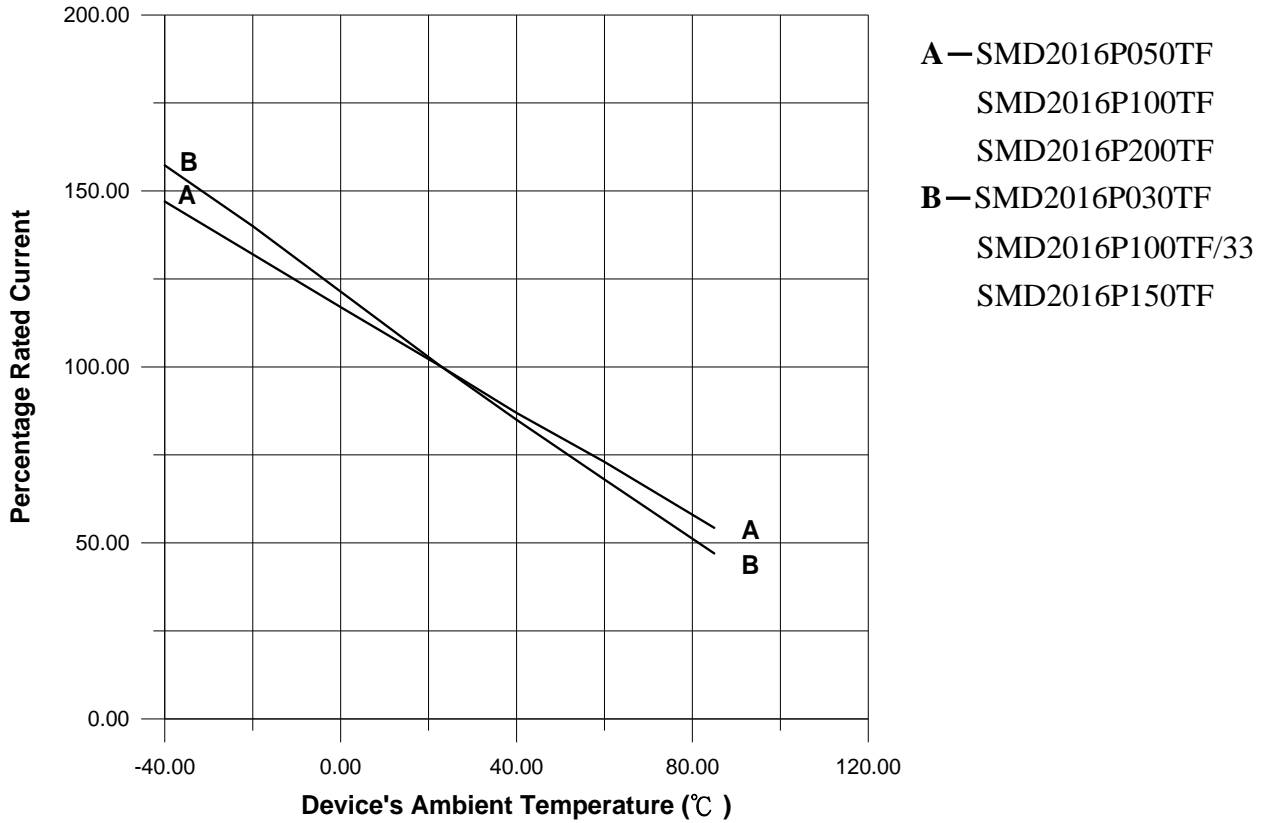


Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

©Specifications are subject to change without notice.

*Customer should verify the device performance in their specified conditions.

THERMAL DERATING CURVE FOR SMD2016 SERIES



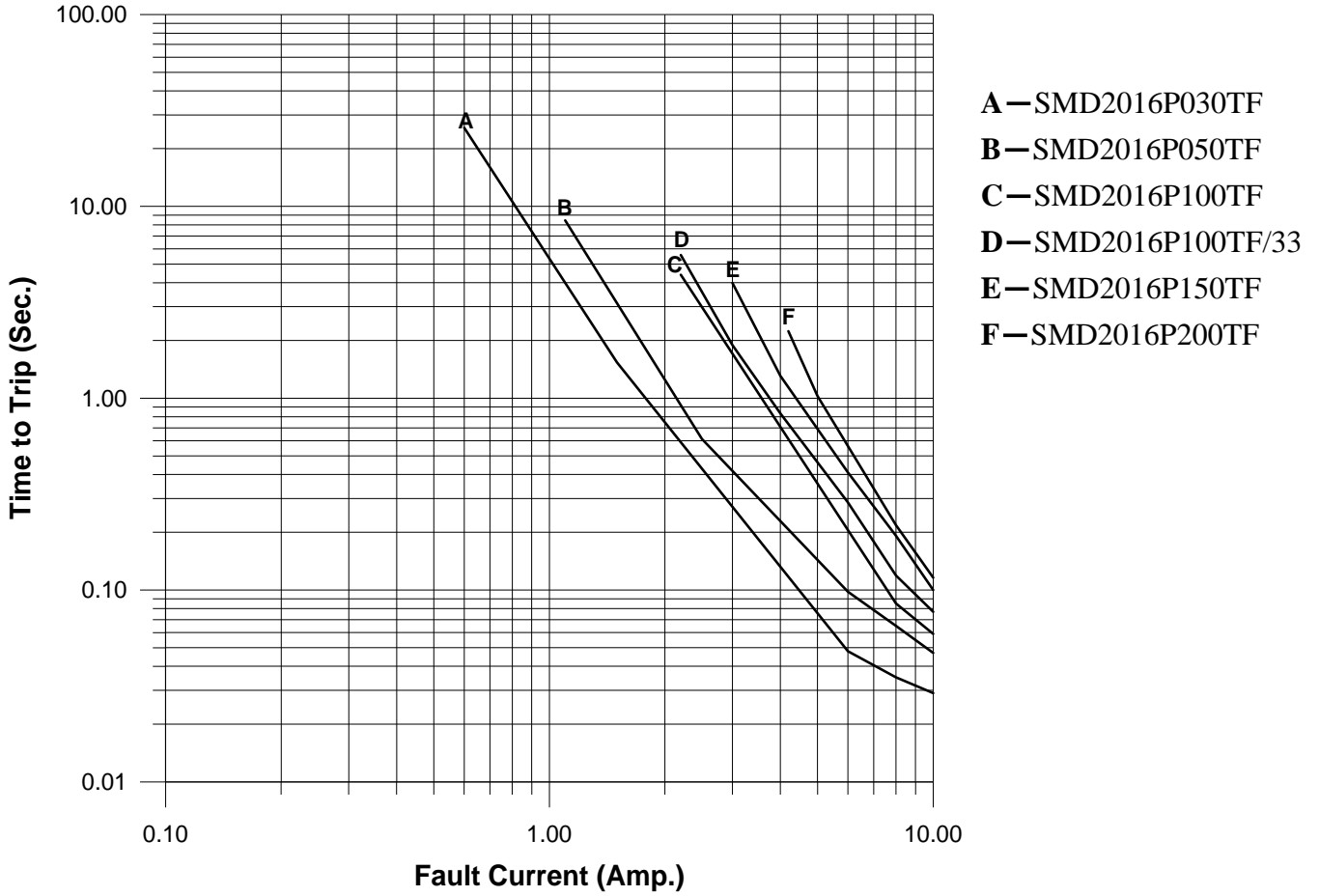
THERMAL DERATING CHART FOR SMD2016 SERIES – Ihold (Amps)

RECOMMENDED DATA

Model	Ambient Operation Temperature								
	-40°C	-20°C	0°C	23°C	40°C	50°C	60°C	70°C	85°C
SMD2016P030TF	0.45	0.40	0.35	0.30	0.25	0.23	0.20	0.18	0.14
SMD2016P050TF	0.93	0.80	0.65	0.50	0.42	0.38	0.33	0.30	0.23
SMD2016P100TF	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
SMD2016P100TF/33	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
SMD2016P150TF	2.26	2.00	1.76	1.50	1.24	1.13	1.00	0.87	0.68
SMD2016P200TF	2.80	2.50	2.19	2.00	1.84	1.74	1.50	1.34	1.14

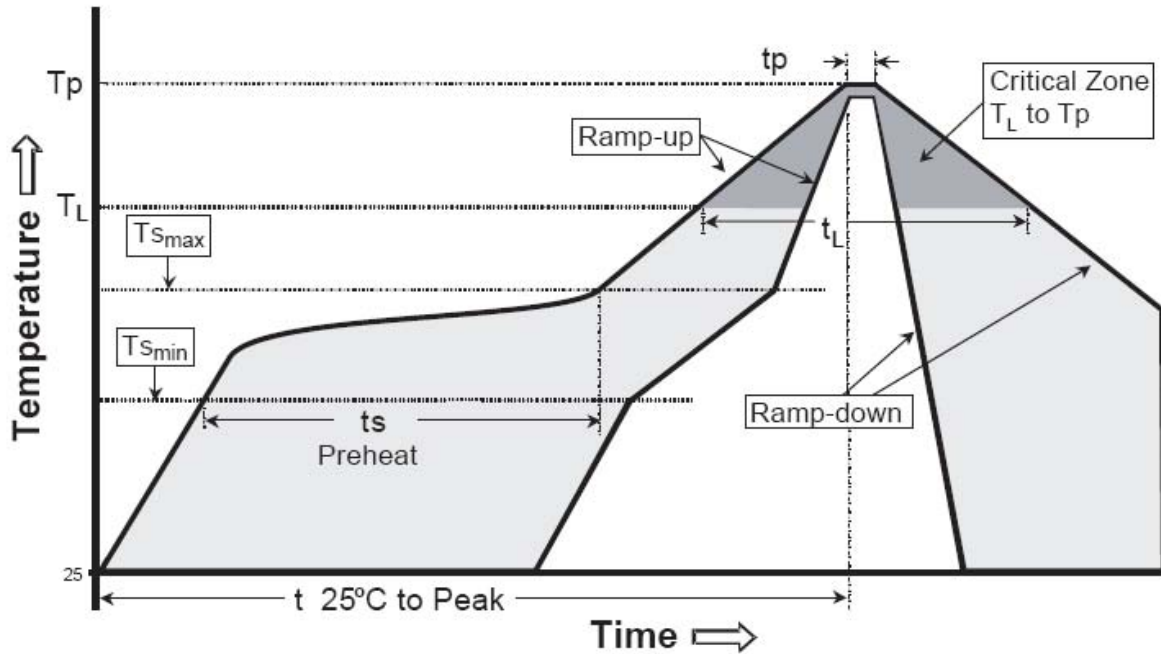
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AVERAGE TIME-CURRENT CURVE FOR SMD2016 SERIES



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SOLDER REFLOW



IPC-020c-5-1

RECOMMENDED CONDITIONS

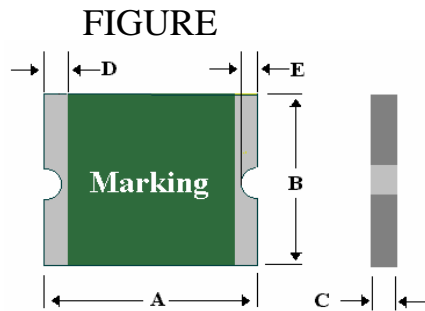
Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T_{smax} to T_p)	3°C/second max.
Preheat	
-Temperature Min (T_{smin})	150°C
-Temperature Max (T_{smax})	200°C
-Time (T_{smin} to T_{smax})	60-180 seconds
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_p)	260°C
Time within 5°C of actual Peak	
Temperature (t_p)	20-40 seconds
Ramp-Down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.
Storage Condition	0°C ~35°C, ≤70%RH

Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead-free
- Recommended maximum paste thickness is 0.25mm (0.010 inch)
- Devices can be cleaned using standard industry methods and solvents.
- Devices can be reworked using the standard industry practices.

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PHYSICAL DIMENSIONS (mm)

Part Number	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
SMD2016P030TF	4.72	5.44	3.70	4.43	0.75	1.25	0.30	1.50	0.25	0.65
SMD2016P050TF	4.72	5.44	3.70	4.43	1.20	2.00	0.30	1.50	0.25	0.65
SMD2016P100TF	4.72	5.44	3.70	4.43	0.50	0.75	0.30	1.50	0.25	0.65
SMD2016P100TF/33	4.72	5.44	3.70	4.43	0.75	1.25	0.30	1.50	0.25	0.65
SMD2016P150TF	4.72	5.44	3.70	4.43	0.75	1.55	0.30	1.50	0.25	0.65
SMD2016P200TF	4.72	5.44	3.70	4.43	0.50	0.75	0.30	1.50	0.25	0.65

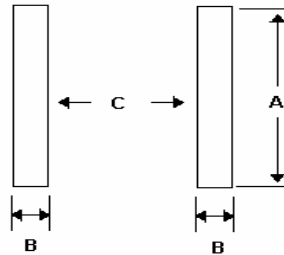
ENVIRONMENTAL SPECIFICATIONS

Operating/Storage Temperature	-40°C to +85°C	
Maximum Device Surface Temperature in Tripped State	125°C	
Passive Aging	+85°C, 1000 hours	±5% typical resistance change
Humidity Aging	+85°C, 85%R.H. 1000 hours	±5% typical resistance change
Thermal Shock	MIL-STD-202 Method 107G +85°C/-40°C 20 times	-30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-883C, Method 2007.1, Condition A	No change

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PACKAGING

SOLDER PAD LAYOUTS
(Dimension in mm)



Part Number	Tape & Reel Quantity	Recommended Pad layout Figure (mm)		
		Dimension (A)	Dimension (B)	Dimension (C)
SMD2016P030TF	1500	4.60	1.50	3.40
SMD2016P050TF	1000	4.60	1.50	3.40
SMD2016P100TF	2000	4.60	1.50	3.40
SMD2016P100TF/33	1500	4.60	1.50	3.40
SMD2016P150TF	1500	4.60	1.50	3.40
SMD2016P200TF	2000	4.60	1.50	3.40

© 12 mm tape on 7 inch reel per EIA-481-1 (equivalent to IEC286, part 3)

PHYSICAL SPECIFICATIONS

Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin(Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.

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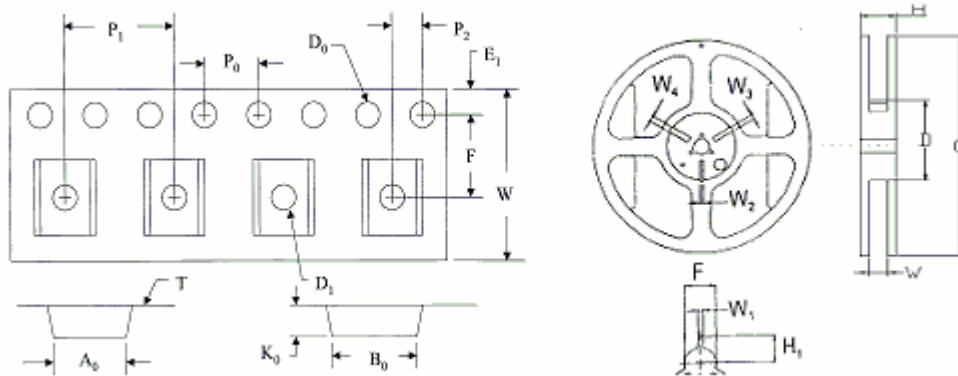
TAPE SPECIFICATIONS: EIA-481-1

REEL DIMENSIONS: EIA-481-1

	P100TF P200TF	P030TF P100TF/33 P150TF	P050TF		
W	12.0+/-0.30	12.0+/-0.30	12.0+/-0.30	H	12.0+/-0.05
F	5.50+/-0.05	5.50+/-0.05	5.50+/-0.05	W	9.0+/-0.5
E ₁	1.75+/-0.10	1.75+/-0.10	1.75+/-0.10	D	Ø60+0.5
D ₀	1.55+/-0.05	1.55+/-0.05	1.55+/-0.05	F	Ø13.0+/-0.2
D ₁	1.50 (MIN)	1.50 (MIN)	1.50 (MIN)	C	Ø178+/-1.0
P ₀	4.0+/-0.10	4.0+/-0.10	4.0+/-0.10	H ₁	11+/-0.5
P ₁	8.0+/-0.10	8.0+/-0.10	8.0+/-0.10	W ₁	2.2+/-0.5
P ₂	2.0+/-0.05	2.0+/-0.05	2.0+/-0.05	W ₂	3.0+0.5
A ₀	4.40+/-0.10	4.48+/-0.10	4.45+/-0.10	W ₃	4.0+0.5
B ₀	5.50+/-0.10	5.40+/-0.10	5.48+/-0.10	W ₄	5.5+0.5
T	0.25+/-0.10	0.25+/-0.10	0.25+/-0.10		
K ₀	0.80+/-0.10	1.36+/-0.10	1.86+/-0.10		
Leader min.	390	390	390		
Trailer min.	160	160	160		

(mm)

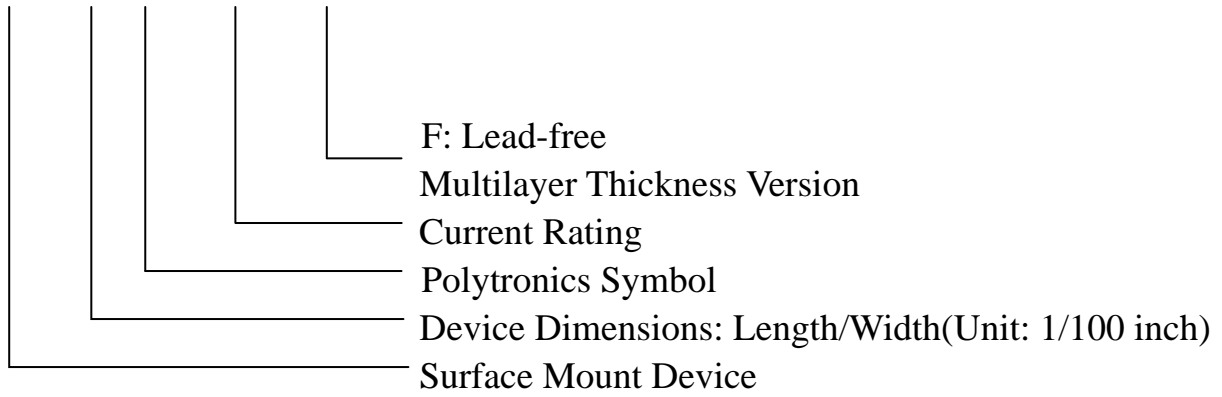
(mm)



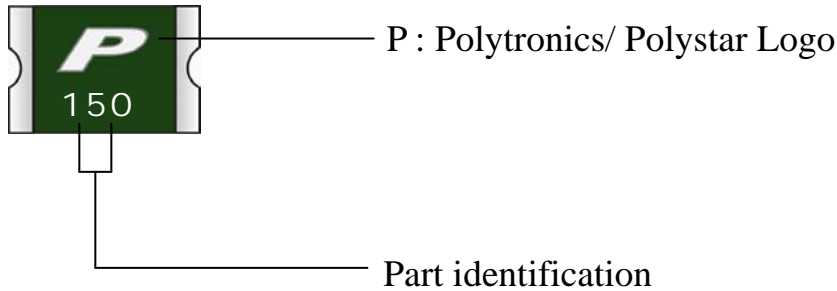
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PART NUMBERING SYSTEM

SMD 2016 P TF



PART MARKING SYSTEM



Note: Polystar is Polytronics's manufacturing site in China. The Polystar ID marking shall appear on smallest package.

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